

# MOS FET WITH SCHOTTKY BARRIER DIODE $\mu$ PA507TE

# P-CHANNEL MOS FET WITH SCHOTTKY BARRIER DIODE FOR SWITCHING

#### **DESCRIPTION**

The  $\mu$  PA507TE is a switching device, which can be driven directly by a 1.8 V power source.

This device incorporates a MOS FET, which features a low on-state resistance and excellent switching characteristics and a low forward voltage Schottky barrier diode, and is suitable for applications such as DC/DC converter of portable machine and so on.

#### **FEATURES**

- 1.8 V drive available (MOS FET)
- Low on-state resistance (MOS FET)

 $R_{DS(on)1} = 68 \text{ m}\Omega \text{ TYP. (V}_{GS} = -4.5 \text{ V}, I_{D} = -1.0 \text{ A})$ 

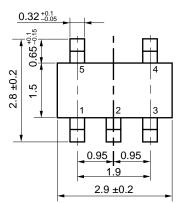
 $R_{DS(on)2} = 84 \text{ m}\Omega \text{ TYP. (V}_{GS} = -2.5 \text{ V}, I_{D} = -1.0 \text{ A})$ 

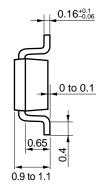
 $R_{DS(on)3} = 109 \text{ m}\Omega \text{ TYP. (V}_{GS} = -1.8 \text{ V}, I_{D} = -1.0 \text{ A})$ 

• Low forward voltage (Schottky barrier diode)

 $V_F = 0.35 \text{ V TYP}. (I_F = 1.0 \text{ A})$ 

#### PACKAGE DRAWING (Unit: mm)



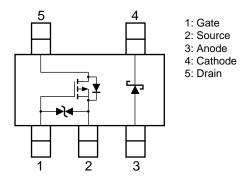


#### ORDERING INFORMATION

| PART NUMBER   | PACKAGE                        |  |  |  |
|---------------|--------------------------------|--|--|--|
| $\mu$ PA507TE | SC-95_5p (Mini Mold Thin Type) |  |  |  |

Marking: ZA

#### **★ PIN CONNECTION (Top View)**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Caution This product is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

V<sub>ESD</sub>  $\pm$  100 V TYP. (C = 200 pF, R = 0  $\Omega$ , Single pulse)

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#### MOS FET ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

| Drain to Source Voltage (V <sub>GS</sub> = 0 V) | VDSS                  | -20  | V  |
|---|-----------------------|------|----|
| Gate to Source Voltage (VDS = 0 V)              | Vgss                  | ∓8   | V  |
| Drain Current (DC)                              | I <sub>D(DC)</sub>    | ∓2   | Α  |
| Drain Current (pulse) Note1                     | I <sub>D(pulse)</sub> | ∓8   | Α  |
| Total Power Dissipation Note2                   | Рт                    | 0.57 | W  |
| Channel Temperature                             | Tch                   | 150  | °C |

#### **Notes 1.** PW $\leq$ 10 $\mu$ s, Duty Cycle $\leq$ 1%

**2.** Mounted on FR-4 board of 2500 mm<sup>2</sup> x 1.6 mm,  $t \le 5$  sec.

#### SCHOTTKY BARRIER DIODE ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

| Repetitive Peak Reverse Voltage | $V_{RRM}$      | 30          | V  |
|---------------------------------|----------------|-------------|----|
| Average Forward Current Note3   | <b>I</b> F(AV) | 1           | Α  |
| Surge Current Note4             | IFSM           | 10          | Α  |
| Junction Temperature            | Tj             | +125        | °C |
| Storage Temperature             | Tstg           | -55 to +125 | °C |

**Notes 3.** Mounted on FR-4 board of 2500 mm<sup>2</sup> x 1.6 mm,  $t \le 5$  sec

4. 50 Hz sine wave, 1 cycle

#### MOS FET ELECTRICAL CHARACTERISTICS (TA = 25°C)

| CHARACTERISTICS                          | SYMBOL               | TEST CONDITIONS                                   | MIN.  | TYP.  | MAX.  | UNIT |
|--|----------------------|---|-------|-------|-------|------|
| Zero Gate Voltage Drain Current          | IDSS                 | V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V    |       |       | -1    | μΑ   |
| Gate Leakage Current                     | Igss                 | $V_{GS} = \mp 8 \text{ V}, V_{DS} = 0 \text{ V}$  |       |       | ∓10   | μΑ   |
| Gate Cut-off Voltage                     | V <sub>GS(off)</sub> | V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1.0 mA | -0.45 | -0.75 | -1.50 | V    |
| Forward Transfer Admittance Note         | yfs                  | V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1.0 A  | 2.0   | 4.3   |       | S    |
| Drain to Source On-state Resistance Note | RDS(on)1             | V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -1.0 A |       | 68    | 85    | mΩ   |
|  | RDS(on)2             | V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -1.0 A |       | 84    | 120   | mΩ   |
|  | RDS(on)3             | V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -1.0 A |       | 109   | 180   | mΩ   |
| Input Capacitance                        | Ciss                 | V <sub>DS</sub> = -10 V                           |       | 380   |       | pF   |
| Output Capacitance                       | Coss                 | V <sub>GS</sub> = 0 V                             |       | 85    |       | pF   |
| Reverse Transfer Capacitance             | Crss                 | f = 1.0 MHz                                       |       | 45    |       | pF   |
| Turn-on Delay Time                       | t <sub>d(on)</sub>   | V <sub>DD</sub> = -10 V, I <sub>D</sub> = -1.0 A  |       | 10    |       | ns   |
| Rise Time                                | tr                   | V <sub>GS</sub> = -4.0 V                          |       | 5     |       | ns   |
| Turn-off Delay Time                      | t <sub>d(off)</sub>  | R <sub>G</sub> = 10 Ω                             |       | 47    |       | ns   |
| Fall Time                                | t <sub>f</sub>       |   |       | 28    |       | ns   |
| Total Gate Charge                        | Q <sub>G</sub>       | V <sub>DD</sub> = -16 V                           |       | 4.7   |       | nC   |
| Gate to Source Charge                    | Qgs                  | V <sub>GS</sub> = -4.0 V                          |       | 0.9   |       | nC   |
| Gate to Drain Charge                     | Q <sub>GD</sub>      | I <sub>D</sub> = -2.0 A                           |       | 1.5   |       | nC   |
| Body Diode Forward Voltage Note          | V <sub>F(S-D)</sub>  | I <sub>F</sub> = 2.0 A, V <sub>GS</sub> = 0 V     |       | 0.84  |       | V    |

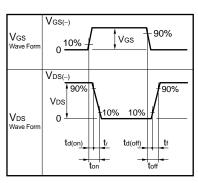
**Note** Pulsed: PW  $\leq$  350  $\mu$ s, Duty Cycle  $\leq$  2%

#### SCHOTTKY BARRIER DIODE ELECTRICAL CHARACTERISTICS (TA = 25°C)

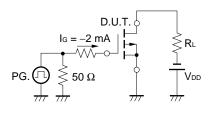
| CHARACTERISTICS      | SYMBOL | TEST CONDITIONS                    | MIN. | TYP. | MAX. | UNIT |
|----------------------|--------|------------------------------------|------|------|------|------|
| Forward Voltage      | VF     | I <sub>F</sub> = 1.0 A             |      | 0.35 | 0.38 | V    |
| Reverse Current      | lR     | V <sub>R</sub> = 10 V              |      |      | 200  | μА   |
| Terminal Capacitance | Ст     | f = 1.0 MHz, V <sub>R</sub> = 10 V |      | 36   |      | pF   |

#### **TEST CIRCUIT 1 SWITCHING TIME**

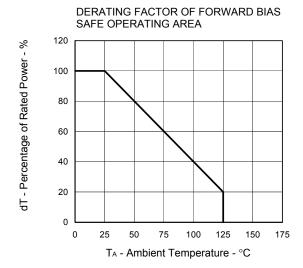
# D.U.T. PG. RG $V_{DD}$ $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$

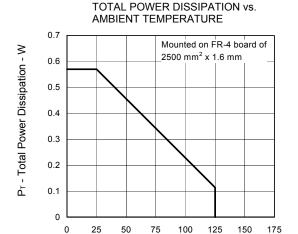


#### **TEST CIRCUIT 2 GATE CHARGE**



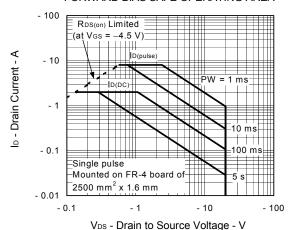
#### MOS FET TYPICAL CHARACTERISTICS (TA = 25°C)



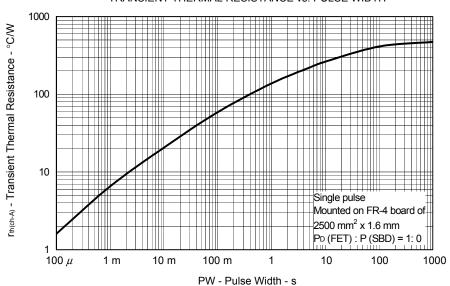


T<sub>A</sub> - Ambient Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



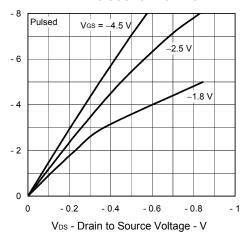
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



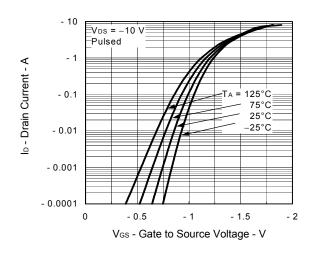
Ip - Drain Current - A

 $R_{DS(m)}$  - Drain to Source On-state Resistance -  $m\Omega$ 

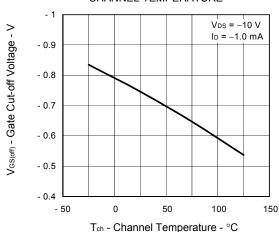
### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



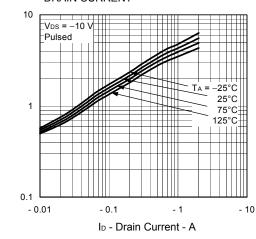
#### FORWARD TRANSFER CHARACTERISTICS



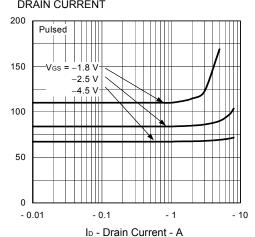
# GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



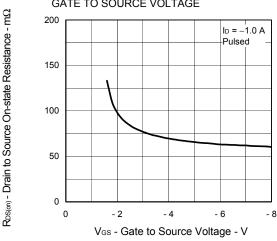
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



# DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

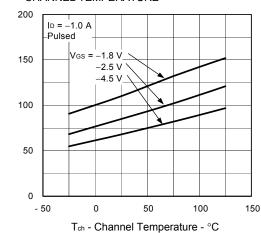


| y<sub>fs</sub> | - Forward Transfer Admittance - S

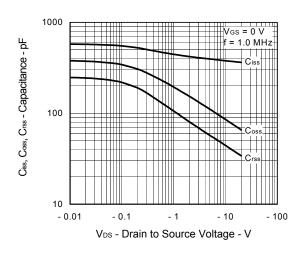
 $\mathsf{R}_{\mathsf{DS}(m)}$  - Drain to Source On-state Resistance -  $m\Omega$ 

td(on), tr, td(off), tr - Switching Time - ns

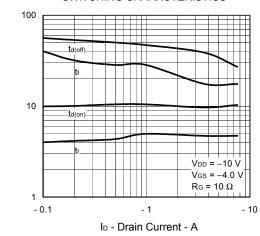
## DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



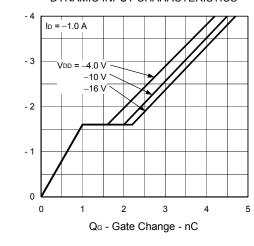
#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



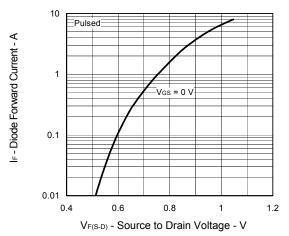
#### SWITCHING CHARACTERISTICS



#### DYNAMIC INPUT CHARACTERISTICS



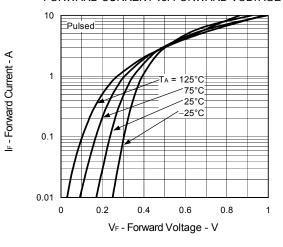
#### SOURCE TO DRAIN DIODE FORWARD VOLTAGE



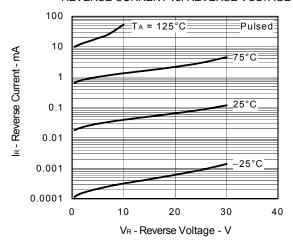
Ves - Gate to Source Voltage - V

#### SCHOTTKY BARRIER DIODE TYPICAL CHARACTERISTICS (TA = 25°C)

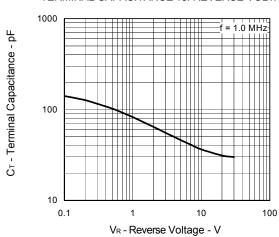
#### FORWARD CURRENT vs. FORWARD VOLTAGE



#### REVERSE CURRENT vs. REVERSE VOLTAGE



#### TERMINAL CAPACITANCE vs. REVERSE VOLTAGE



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